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#### Details

Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.295", 7.50mm Width)
Supplier Device Package	16-SOIC
Purchase URL	<a href="https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=mc908kx2cdwer">https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=mc908kx2cdwer</a>

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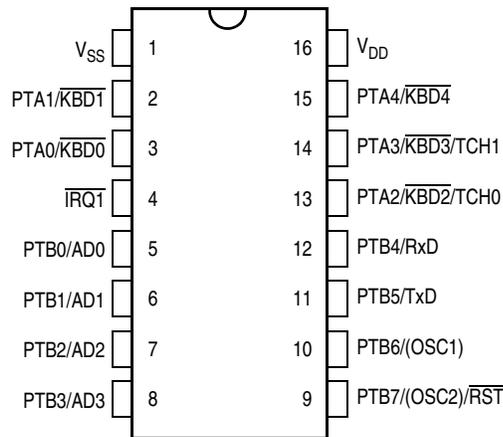
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## 1.4 Pin Assignments

Figure 1-2 shows the pin assignments for MC68HC908KX8.

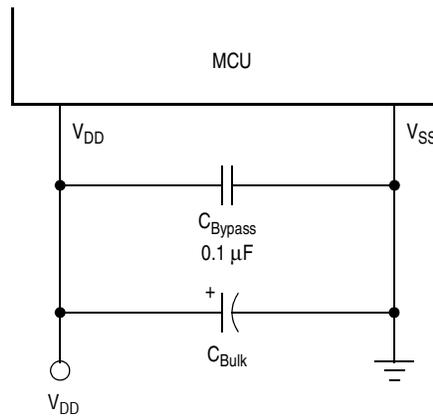


**Figure 1-2. PDIP and SOIC Pin Assignments**

### 1.4.1 Supply Pins ( $V_{DD}$ and $V_{SS}$ )

$V_{DD}$  and  $V_{SS}$  are the power supply and ground pins. The MCU operates from a single power supply.

Fast signal transitions on MCU pins place high, short-duration current demands on the power supply. To prevent noise problems, take special care to provide power supply bypassing at the MCU as shown in Figure 1-3. Place the bypass capacitors as close to the MCU power pins as possible. Use high-frequency response ceramic capacitors for  $C_{Bypass}$ .  $C_{Bulk}$  are optional bulk current bypass capacitors for use in applications that require the port pins to source high-current levels.

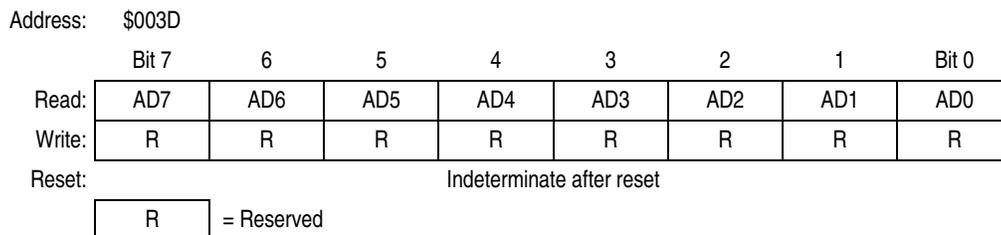


Note: Component values shown represent typical applications.

**Figure 1-3. Power Supply Bypassing**

### 3.7.2 ADC Data Register

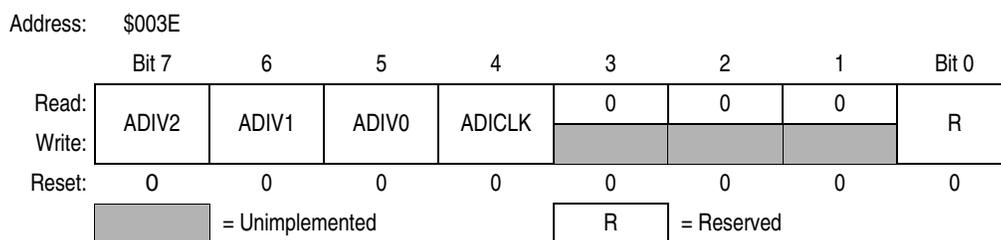
One 8-bit result register is provided. This register is updated each time an ADC conversion completes.



**Figure 3-4. ADC Data Register (ADR)**

### 3.7.3 ADC Input Clock Register

This register selects the clock frequency for the ADC.



**Figure 3-5. ADC Input Clock Register (ADICLK)**

#### ADIV2–ADIV0 — ADC Clock Prescaler Bits

ADIV2, ADIV1, and ADIV0 form a 3-bit field which selects the divide ratio used by the ADC to generate the internal ADC clock. Table 3-2 shows the available clock configurations. The ADC clock should be set to approximately 1 MHz.

**Table 3-2. ADC Clock Divide Ratio**

ADIV2	ADIV1	ADIV0	ADC Clock Rate
0	0	0	ADC input clock ÷ 1
0	0	1	ADC input clock ÷ 2
0	1	0	ADC input clock ÷ 4
0	1	1	ADC input clock ÷ 8
1	X	X	ADC input clock ÷ 16

X = don't care

#### ADICLK — ADC Input Clock Select Bit

ADICLK selects either bus clock or the oscillator output clock (CGMXCLK) as the input clock source to generate the internal ADC rate clock. Reset selects CGMXCLK as the ADC clock source.

1 = Internal bus clock

0 = Oscillator output clock (CGMXCLK)

Clearing the EXTXTALEN bit (default setting) allows the PTB7/(OSC2)/ $\overline{\text{RST}}$  pin to function as a general-purpose I/O pin. Refer to Table 4-1 for configuration options for the external source. See Chapter 7 Internal Clock Generator Module (ICG) for a more detailed description of the external clock operation.

EXTXTALEN, when set, also configures the clock monitor to expect an external clock source in the valid range of crystals (30 kHz to 100 kHz or 1 MHz to 8 MHz). When EXTXTALEN is clear, the clock monitor will expect an external clock source in the valid range for externally generated clocks when using the clock monitor (60 Hz to 32 MHz).

EXTXTALEN, when set, also configures the external clock stabilization divider in the clock monitor for a 4096-cycle timeout to allow the proper stabilization time for a crystal. When EXTXTALEN is clear, the stabilization divider is configured to 16 cycles since an external clock source does not need a startup time.

- 1 = Allows PTB7/(OSC2)/ $\overline{\text{RST}}$  to be an external crystal connection.
- 0 = PTB7/(OSC2)/ $\overline{\text{RST}}$  functions as an I/O port pin (default).

#### OSCENINSTOP — Oscillator Enable In Stop Mode Bit

OSCENINSTOP, when set, will enable the internal clock generator module to continue to generate clocks (either internal, ICLK, or external, ECLK) in stop mode. See Chapter 7 Internal Clock Generator Module (ICG). This function is used to keep the timebase running while the rest of the microcontroller stops. See Chapter 14 Timebase Module (TBM). When clear, all clock generation will cease and both ICLK and ECLK will be forced low during stop mode. The default state for this option is clear, disabling the ICG in stop mode.

- 1 = Oscillator enabled to operate during stop mode
- 0 = Oscillator disabled during stop mode (default)

#### NOTE

*This bit has the same functionality as the OSCSTOPENB CONFIG bit in MC68HC908GP20 and MC68HC908GR8 parts.*

#### SCIBDSRC — SCI Baud Rate Clock Source Bit

SCIBDSRC controls the clock source used for the SCI. The setting of this bit affects the frequency at which the SCI operates.

- 1 = Internal data bus clock is used as clock source for SCI.
- 0 = CGMXCLK is used as clock source for SCI.

#### COPRS — COP Rate Select Bit

COPD selects the COP timeout period. Reset clears COPRS. See Chapter 5 Computer Operating Properly Module (COP).

- 1 = COP timeout period =  $2^{13} - 2^4$  CGMXCLK cycles
- 0 = COP timeout period =  $2^{18} - 2^4$  CGMXCLK cycles

#### LVISTOP — LVI Enable in Stop Mode Bit

When the LVIPWRD bit is clear, setting the LVISTOP bit enables the LVI to operate during stop mode. Reset clears LVISTOP.

- 1 = LVI enabled during stop mode
- 0 = LVI disabled during stop mode

#### LVIRSTD — LVI Reset Disable Bit

LVIRSTD disables the reset signal from the LVI module. See Chapter 10 Low-Voltage Inhibit (LVI).

- 1 = LVI module resets disabled
- 0 = LVI module resets enabled

Table 6-1. Instruction Set Summary (Sheet 3 of 6)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles	
			V	H	I	N	Z					C
CLR <i>opr</i> CLRA CLR <sub>X</sub> CLR <sub>H</sub> CLR <i>opr</i> , <i>X</i> CLR <i>,X</i> CLR <i>opr</i> ,SP	Clear	M ← \$00 A ← \$00 X ← \$00 H ← \$00 M ← \$00 M ← \$00 M ← \$00	0	-	-	0	1	-	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	dd  ff ff	3 1 1 1 3 2 4
CMP # <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> , <i>X</i> CMP <i>opr</i> , <i>X</i> CMP <i>,X</i> CMP <i>opr</i> ,SP CMP <i>opr</i> ,SP	Compare A with M	(A) - (M)	†	-	-	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A1 B1 C1 D1 E1 F1 9EE1 9ED1	ii dd hh ll ee ff ff ff ff ff	2 3 4 4 3 2 4 5
COM <i>opr</i> COMA COM <sub>X</sub> COM <i>opr</i> , <i>X</i> COM <i>,X</i> COM <i>opr</i> ,SP	Complement (One's Complement)	M ← (M) = \$FF - (M) A ← (A) = \$FF - (M) X ← (X) = \$FF - (M) M ← (M) = \$FF - (M) M ← (M) = \$FF - (M) M ← (M) = \$FF - (M)	0	-	-	†	†	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd  ff ff	4 1 1 4 3 5
CPHX # <i>opr</i> CPHX <i>opr</i>	Compare H:X with M	(H:X) - (M:M + 1)	†	-	-	†	†	†	IMM DIR	65 75	ii ii+1 dd	3 4
CPX # <i>opr</i> CPX <i>opr</i> CPX <i>opr</i> CPX <i>,X</i> CPX <i>opr</i> , <i>X</i> CPX <i>opr</i> , <i>X</i> CPX <i>opr</i> ,SP CPX <i>opr</i> ,SP	Compare X with M	(X) - (M)	†	-	-	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A3 B3 C3 D3 E3 F3 9EE3 9ED3	ii dd hh ll ee ff ff ff ff	2 3 4 4 3 2 4 5
DAA	Decimal Adjust A	(A) <sub>10</sub>	U	-	-	†	†	†	INH	72		2
DBNZ <i>opr,rel</i> DBNZ <sub>A</sub> <i>rel</i> DBNZ <sub>X</sub> <i>rel</i> DBNZ <i>opr,X,rel</i> DBNZ <i>X,rel</i> DBNZ <i>opr,SP,rel</i>	Decrement and Branch if Not Zero	A ← (A) - 1 or M ← (M) - 1 or X ← (X) - 1 PC ← (PC) + 3 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 3 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 4 + <i>rel</i> ? (result) ≠ 0	-	-	-	-	-	-	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr ff rr rr ff rr	5 3 3 5 4 6
DEC <i>opr</i> DECA DEC <sub>X</sub> DEC <i>opr</i> , <i>X</i> DEC <i>,X</i> DEC <i>opr</i> ,SP	Decrement	M ← (M) - 1 A ← (A) - 1 X ← (X) - 1 M ← (M) - 1 M ← (M) - 1 M ← (M) - 1	†	-	-	†	†	-	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd  ff ff	4 1 1 4 3 5
DIV	Divide	A ← (H:A)/(X) H ← Remainder	-	-	-	-	†	†	INH	52		7
EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> , <i>X</i> EOR <i>opr</i> , <i>X</i> EOR <i>,X</i> EOR <i>opr</i> ,SP EOR <i>opr</i> ,SP	Exclusive OR M with A	A ← (A ⊕ M)	0	-	-	†	†	-	IMM DIR EXT IX2 IX1 IX SP1 SP2	A8 B8 C8 D8 E8 F8 9EE8 9ED8	ii dd hh ll ee ff ff ff ff	2 3 4 4 3 2 4 5
INC <i>opr</i> INCA INC <sub>X</sub> INC <i>opr</i> , <i>X</i> INC <i>,X</i> INC <i>opr</i> ,SP	Increment	M ← (M) + 1 A ← (A) + 1 X ← (X) + 1 M ← (M) + 1 M ← (M) + 1 M ← (M) + 1	†	-	-	†	†	-	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd  ff ff	4 1 1 4 3 5

# Chapter 7

## Internal Clock Generator Module (ICG)

### 7.1 Introduction

The internal clock generator module (ICG) is used to create a stable clock source for the microcontroller without using any external components. The ICG generates the oscillator output clock (CGMXCLK), which is used by the computer operating properly (COP), low-voltage inhibit (LVI), and other modules. The ICG also generates the clock generator output (CGMOUT), which is fed to the system integration module (SIM) to create the bus clocks. The bus frequency will be one-fourth the frequency of CGMXCLK and one-half the frequency of CGMOUT. Finally, the ICG generates the timebase clock (TBMCLK), which is used in the timebase module (TBM).

### 7.2 Features

Features of the ICG include:

- Selectable external clock generator, either one pin external source or two pin crystal, multiplexed with port pins
- Internal clock generator with programmable frequency output in integer multiples of a nominal frequency (307.2 kHz  $\pm$  25%)
- Frequency adjust (trim) register to improve variability to  $\pm$  2%
- Bus clock software selectable from either internal or external clock (bus frequency range from 76.8 kHz  $\pm$  25% to 9.75 MHz  $\pm$  25% in 76.8 kHz increments — note that for the MC68HC908KX8, MC68HC908KX2, and MC68HC08KX8, do not exceed the maximum bus frequency of 8 MHz at 5.0 V and 4 MHz at 3.0 V)
- Timebase clock automatically selected externally, if external clock is available
- Clock monitor for both internal and external clocks

### 7.3 Functional Description

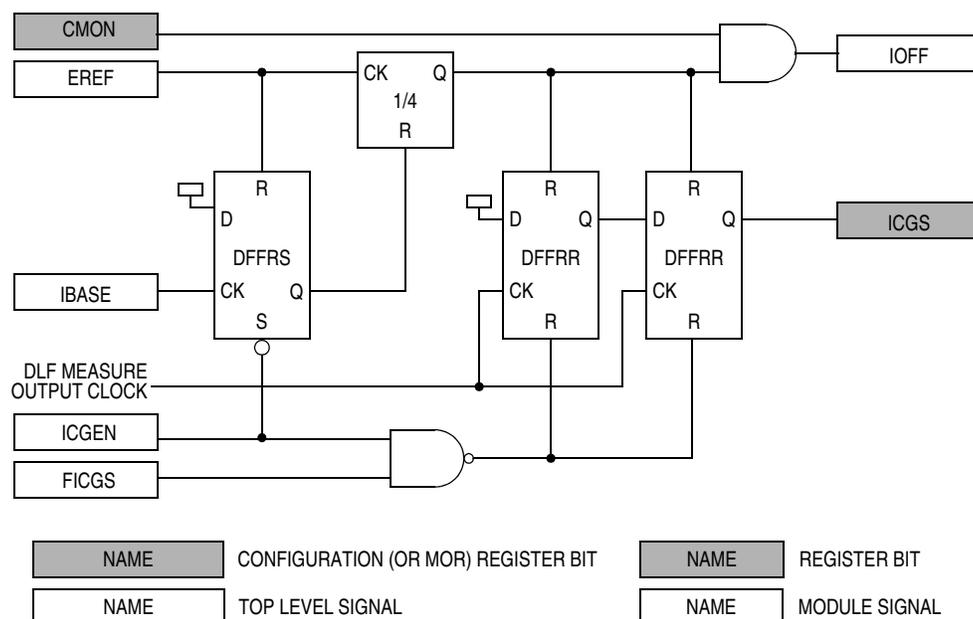
As shown in Figure 7-1, the ICG contains these major submodules:

- Clock enable circuit
- Internal clock generator
- External clock generator
- Clock monitor circuit
- Clock selection circuit

### 7.3.4.2 Internal Clock Activity Detector

The internal clock activity detector, shown in Figure 7-5, looks for at least one falling edge on the low-frequency base clock (IBASE) every time the external reference (EREF) is low. Since EREF is less than half the frequency of IBASE, this should occur every time. If it does not occur two consecutive times, the internal clock inactivity indicator (IOFF) is set. IOFF will be cleared the next time there is a falling edge of IBASE while EREF is low.

The internal clock stable bit (ICGS) is also generated in the internal clock activity detector. ICGS is set when the internal clock generator's filter stable signal (FICGS) indicates that IBASE is within about 15% of the target  $307.2 \text{ kHz} \pm 25\%$  for two consecutive measurements. ICGS is cleared when FICGS is clear, the internal clock generator is turned off or in STOP (ICGEN is clear), or when IOFF is set.



**Figure 7-5. Internal Clock Activity Detector**

### 7.3.4.3 External Clock Activity Detector

The external clock activity detector, shown in Figure 7-6, looks for at least one falling edge on the external clock (ECLK) every time the internal reference (IREF) is low. Since IREF is less than half the frequency of ECLK, this should occur every time. If it does not occur two consecutive times, the external clock inactivity indicator (EOFF) is set. EOFF will be cleared the next time there is a falling edge of ECLK while IREF is low.

The external clock stable bit (ECGS) is also generated in the external clock activity detector. ECGS is set on a falling edge of the external stabilization clock (ESTBCLK). This will be 4096 ECLK cycles after the external clock generator on bit is set or the MCU exits STOP (ECGEN = 1) if the external crystal enable (EXTXTALEN) in the CONFIG (or MOR) register is set, or 16 cycles when EXTXTALEN is clear. ECGS is cleared when the external clock generator is turned off or in STOP (ECGEN is clear) or when EOFF is set.

# Chapter 12

## Serial Communications Interface Module (SCI)

### 12.1 Introduction

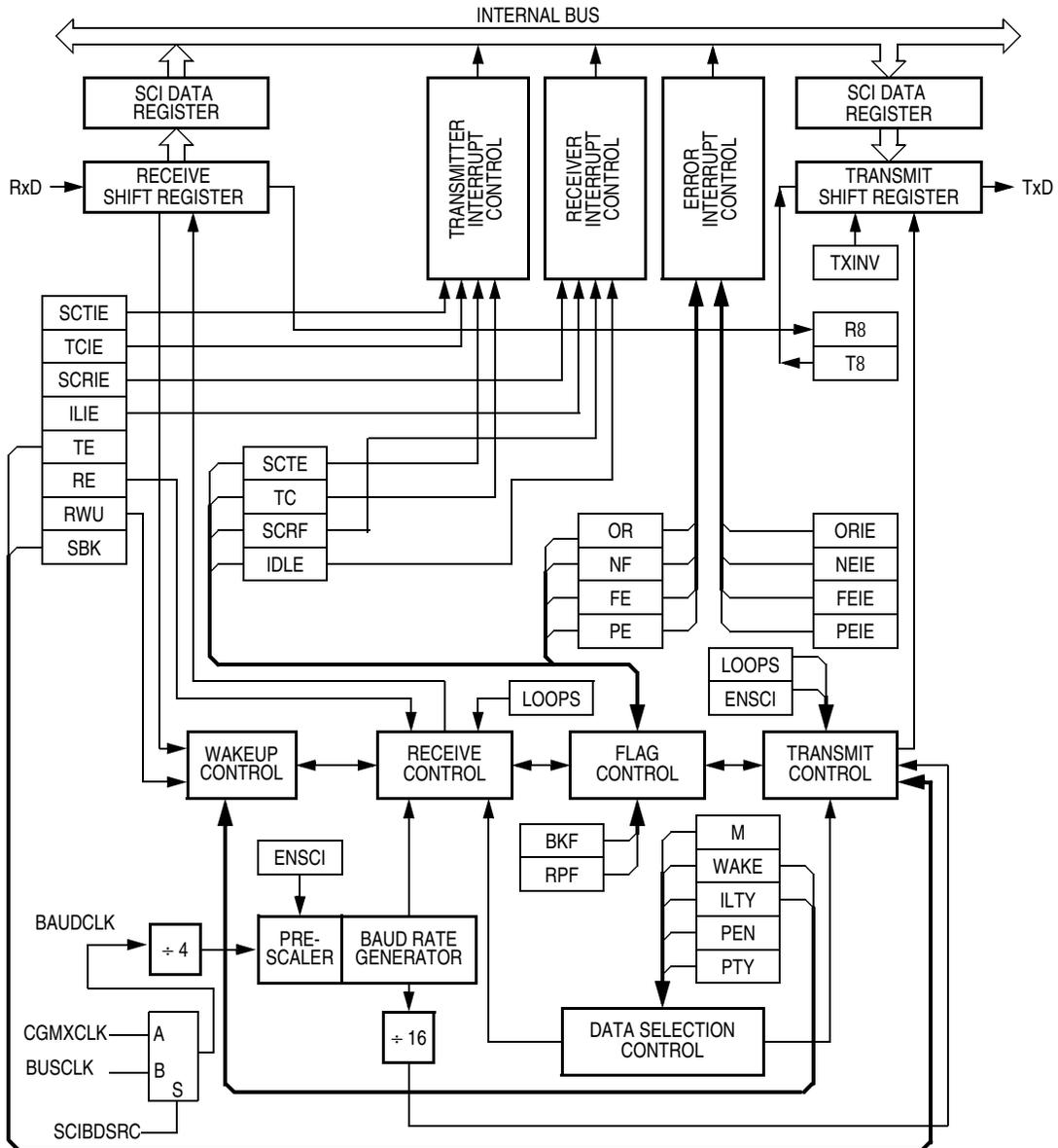
The serial communications interface (SCI) allows asynchronous communications with peripheral devices and other microcontroller unit (MCU).

### 12.2 Features

The SCI module's features include:

- Full-duplex operation
- Standard mark/space non-return-to-zero (NRZ) format
- Choice of baud rate clock source:
  - Internal bus clock
  - CGMXCLK
- 32 programmable baud rates
- Programmable 8-bit or 9-bit character length
- Separately enabled transmitter and receiver
- Separate receiver and transmitter central processor unit (CPU) interrupt requests
- Programmable transmitter output polarity
- Two receiver wakeup methods:
  - Idle line wakeup
  - Address mark wakeup
- Interrupt-driven operation with eight interrupt flags:
  - Transmitter empty
  - Transmission complete
  - Receiver full
  - Idle receiver input
  - Receiver overrun
  - Noise error
  - Framing error
  - Parity error
- Receiver framing error detection
- Hardware parity checking
- 1/16 bit-time noise detection

# Serial Communications Interface Module (SCI)



**Figure 12-3. SCI Module Block Diagram**

### SCRIE — SCI Receive Interrupt Enable Bit

This read/write bit enables the SCRF bit to generate SCI receiver CPU interrupt requests. Setting the SCRIE bit in SCC3 enables the SCRF bit to generate CPU interrupt requests. Reset clears the SCRIE bit.

- 1 = SCRF enabled to generate CPU interrupt
- 0 = SCRF not enabled to generate CPU interrupt

### ILIE — Idle Line Interrupt Enable Bit

This read/write bit enables the IDLE bit to generate SCI receiver CPU interrupt requests. Reset clears the ILIE bit.

- 1 = IDLE enabled to generate CPU interrupt requests
- 0 = IDLE not enabled to generate CPU interrupt requests

### TE — Transmitter Enable Bit

Setting this read/write bit begins the transmission by sending a preamble of 10 or 11 1s from the transmit shift register to the TxD pin. If software clears the TE bit, the transmitter completes any transmission in progress before the TxD returns to the idle condition (logic 1). Clearing and then setting TE during a transmission queues an idle character to be sent after the character currently being transmitted. Reset clears the TE bit.

- 1 = Transmitter enabled
- 0 = Transmitter disabled

#### NOTE

*Writing to the TE bit is not allowed when the enable SCI bit (ENSCI) is clear. ENSCI is in SCI control register 1.*

### RE — Receiver Enable Bit

Setting this read/write bit enables the receiver. Clearing the RE bit disables the receiver but does not affect receiver interrupt flag bits. Reset clears the RE bit.

- 1 = Receiver enabled
- 0 = Receiver disabled

#### NOTE

*Writing to the RE bit is not allowed when the enable SCI bit (ENSCI) is clear. ENSCI is in SCI control register 1.*

### RWU — Receiver Wakeup Bit

This read/write bit puts the receiver in a standby state during which receiver interrupts are disabled. The WAKE bit in SCC1 determines whether an idle input or an address mark brings the receiver out of the standby state and clears the RWU bit. Reset clears the RWU bit.

- 1 = Standby state
- 0 = Normal operation

### SBK — Send Break Bit

Setting and then clearing this read/write bit transmits a break character followed by a 1. The 1 after the break character guarantees recognition of a valid start bit. If SBK remains set, the transmitter continuously transmits break characters with no 1s between them. Reset clears the SBK bit.

- 1 = Transmit break characters
- 0 = No break characters being transmitted

#### NOTE

*Do not toggle the SBK bit immediately after setting the SCTE bit. Toggling SBK before the preamble begins causes the SCI to send a break character instead of a preamble.*

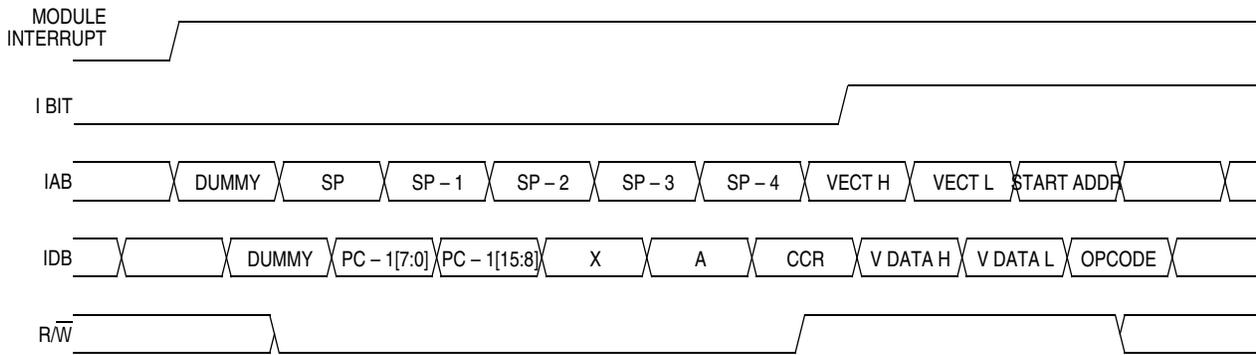
## 13.5 Program Exception Control

Normal, sequential program execution can be changed in two ways:

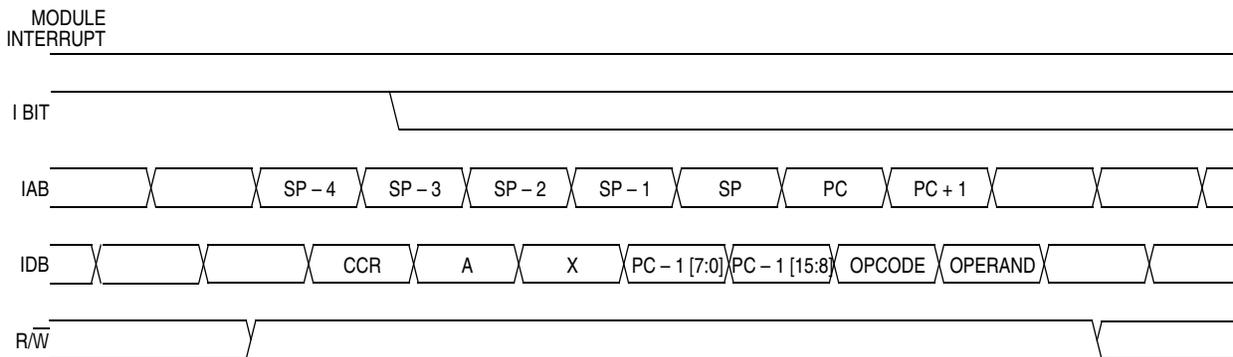
1. Interrupts
  - a. Maskable hardware CPU interrupts
  - b. Non-maskable software interrupt instruction (SWI)
2. Reset

### 13.5.1 Interrupts

At the beginning of an interrupt, the CPU saves the CPU register contents on the stack and sets the interrupt mask (I bit) to prevent additional interrupts. At the end of an interrupt, the return-from-interrupt (RTI) instruction recovers the CPU register contents from the stack so that normal processing can resume. Figure 13-7 shows interrupt entry timing. Figure 13-8 shows interrupt recovery timing.



**Figure 13-7. Interrupt Entry**



**Figure 13-8. Interrupt Recovery**

Interrupts are latched, and arbitration is performed in the SIM at the start of interrupt processing. The arbitration result is a constant that the CPU uses to determine which vector to fetch. As shown in Figure 13-9, once an interrupt is latched by the SIM, no other interrupt can take precedence, regardless of priority, until the latched interrupt is serviced or the I bit is cleared.

# Timebase Module (TBM)

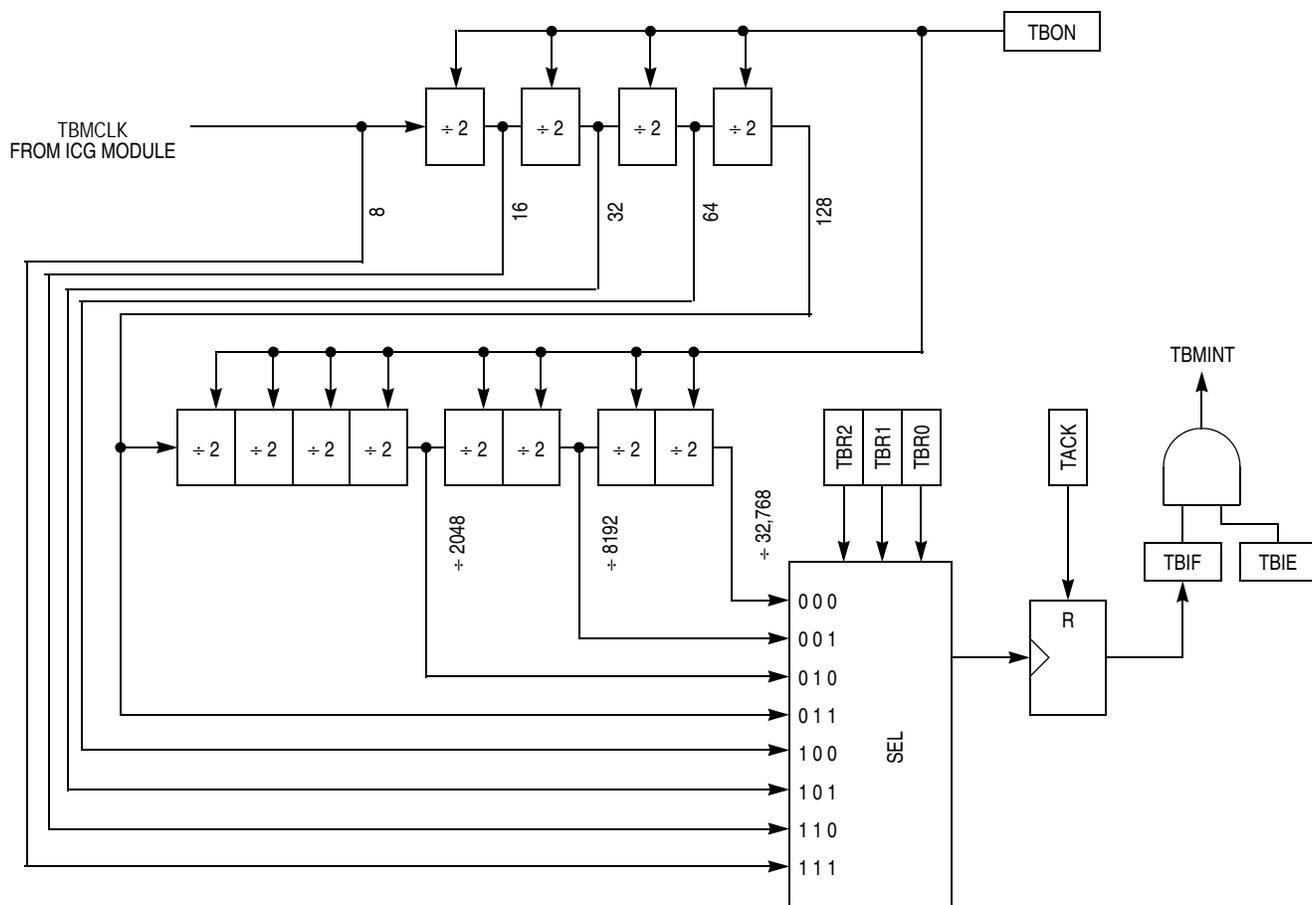


Figure 14-1. Timebase Block Diagram

### 15.4.4 Unbuffered Output Compare

Any output compare channel can generate unbuffered output compare pulses as described in 15.4.3 Output Compare. The pulses are unbuffered because changing the output compare value requires writing the new value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change an output compare value could cause incorrect operation for up to two counter overflow periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that counter overflow period. Also, using a TIM overflow interrupt routine to write a new, smaller output compare value may cause the compare to be missed. The TIM may pass the new value before it is written.

Use these methods to synchronize unbuffered changes in the output compare value on channel x:

- When changing to a smaller value, enable channel x output compare interrupts and write the new value in the output compare interrupt routine. The output compare interrupt occurs at the end of the current output compare pulse. The interrupt routine has until the end of the counter overflow period to write the new value.
- When changing to a larger output compare value, enable TIM overflow interrupts and write the new value in the TIM overflow interrupt routine. The TIM overflow interrupt occurs at the end of the current counter overflow period. Writing a larger value in an output compare interrupt routine (at the end of the current pulse) could cause two output compares to occur in the same counter overflow period.

### 15.4.5 Buffered Output Compare

Channels 0 and 1 can be linked to form a buffered output compare channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The output compare value in the TIM channel 0 registers initially controls the output on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the output after the TIM overflows. At each subsequent overflow, the TIM channel registers (0 or 1) that control the output are the 1s written to last. TSC0 controls and monitors the buffered output compare function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

#### **NOTE**

*In buffered output compare operation, do not write new output compare values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered output compares.*

### 15.4.6 Pulse-Width Modulation (PWM)

By using the toggle-on-overflow feature with an output compare channel, the TIM can generate a PWM signal. The value in the TIM counter modulo registers determines the period of the PWM signal. The channel pin toggles when the counter reaches the value in the TIM counter modulo registers. The time between overflows is the period of the PWM signal.

As Figure 15-4 shows, the output compare value in the TIM channel registers determines the pulse width of the PWM signal. The time between overflow and output compare is the pulse width. Program the TIM

## Timer Interface Module (TIM)

- In the TIM status control register (TSC), clear the TIM stop bit, TSTOP.

Setting MS0B links channels 0 and 1 and configures them for buffered PWM operation. The TIM channel 0 registers (TCH0H and TCH0L) initially control the buffered PWM output. TIM status control register 0 (TSCR0) controls and monitors the PWM signal from the linked channels.

Clearing the toggle-on-overflow bit, TOVx, inhibits output toggles on TIM overflows. Subsequent output compares try to force the output to a state it is already in and have no effect. The result is a 0 percent duty cycle output.

Setting the channel x maximum duty cycle bit (CHxMAX) and setting the TOVx bit generates a 100 percent duty cycle output. See 15.8.4 TIM Channel Status and Control Registers.

## 15.5 Interrupts

These TIM sources can generate interrupt requests:

- TIM overflow flag (TOF) — The timer overflow flag (TOF) bit is set when the TIM counter reaches the modulo value programmed in the TIM counter modulo registers. The TIM overflow interrupt enable bit, TOIE, enables TIM overflow interrupt requests. TOF and TOIE are in the TIM status and control registers.
- TIM channel flags (CH1F and CH0F) — The CHxF bit is set when an input capture or output compare occurs on channel x. Channel x TIM CPU interrupt requests are controlled by the channel x interrupt enable bit, CHxIE. Channel x TIM CPU interrupt requests are enabled when CHxIE = 1. CHxF and CHxIE are in the TIM channel x status and control register.

## 15.6 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

### 15.6.1 Wait Mode

The TIM remains active after the execution of a WAIT instruction. In wait mode the TIM registers are not accessible by the CPU. Any enabled CPU interrupt request from the TIM can bring the MCU out of wait mode.

If TIM functions are not required during wait mode, reduce power consumption by stopping the TIM before executing the WAIT instruction.

### 15.6.2 Stop Mode

The TIM is inactive after the execution of a STOP instruction. The STOP instruction does not affect register conditions or the state of the TIM counter. TIM operation resumes when the MCU exits stop mode after an external interrupt.

## 15.7 I/O Signals

Port A shares two of its pins with the TIM, PTA3/ $\overline{\text{KBD3}}$ /TCH1 and PTA2/ $\overline{\text{KBD2}}$ /TCH0. Each channel input/output (I/O) pin is programmable independently as an input capture pin or an output compare pin. TCH0 can be configured as buffered output compare or buffered PWM pins.

**Table 15-3. Mode, Edge, and Level Selection**

MSxB	MSxA	ELSxB	ELSxA	Mode	Configuration
X	0	0	0	Output preset	Pin under port control; initial output level high
X	1	0	0		Pin under port control; initial output level low
0	0	0	1	Input capture	Capture on rising edge only
0	0	1	0		Capture on falling edge only
0	0	1	1		Capture on rising or falling edge
0	1	0	0	Output compare or PWM	Software compare only
0	1	0	1		Toggle output on compare
0	1	1	0		Clear output on compare
0	1	1	1		Set output on compare
1	X	0	1	Buffered output compare or buffered PWM	Toggle output on compare
1	X	1	0		Clear output on compare
1	X	1	1		Set output on compare

**NOTE**

*Before enabling a TIM channel register for input capture operation, make sure that the PTAx/TCHx pin is stable for at least two bus clocks.*

**TOVx — Toggle On Overflow Bit**

When channel x is an output compare channel, this read/write bit controls the behavior of the channel x output when the TIM counter overflows. When channel x is an input capture channel, TOVx has no effect. Reset clears the TOVx bit.

1 = Channel x pin toggles on TIM counter overflow.

0 = Channel x pin does not toggle on TIM counter overflow.

**NOTE**

*When TOVx is set, a TIM counter overflow takes precedence over a channel x output compare if both occur at the same time.*

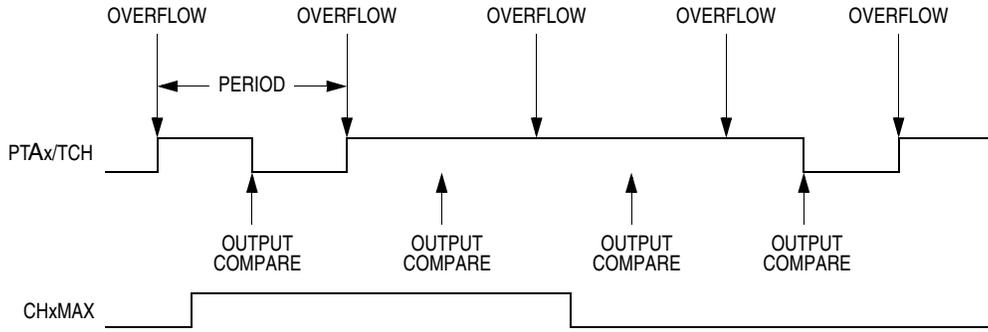
**CHxMAX — Channel x Maximum Duty Cycle Bit**

When the TOVx bit is at 1 and clear output on compare is selected, setting the CHxMAX bit forces the duty cycle of buffered and unbuffered PWM signals to 100 percent. As Figure 15-9 shows, the CHxMAX bit takes effect in the cycle after it is set or cleared. The output stays at 100 percent duty cycle level until the cycle after CHxMAX is cleared.

**NOTE**

*The PWM 0 percent duty cycle is defined as output low all of the time. To generate the 0 percent duty cycle, select clear output on compare and then clear the TOVx bit (CHxMAX = 0). The PWM 100 percent duty cycle is defined as output high all of the time. To generate the 100 percent duty cycle, use the CHxMAX bit in the TSCx register.*

## Timer Interface Module (TIM)



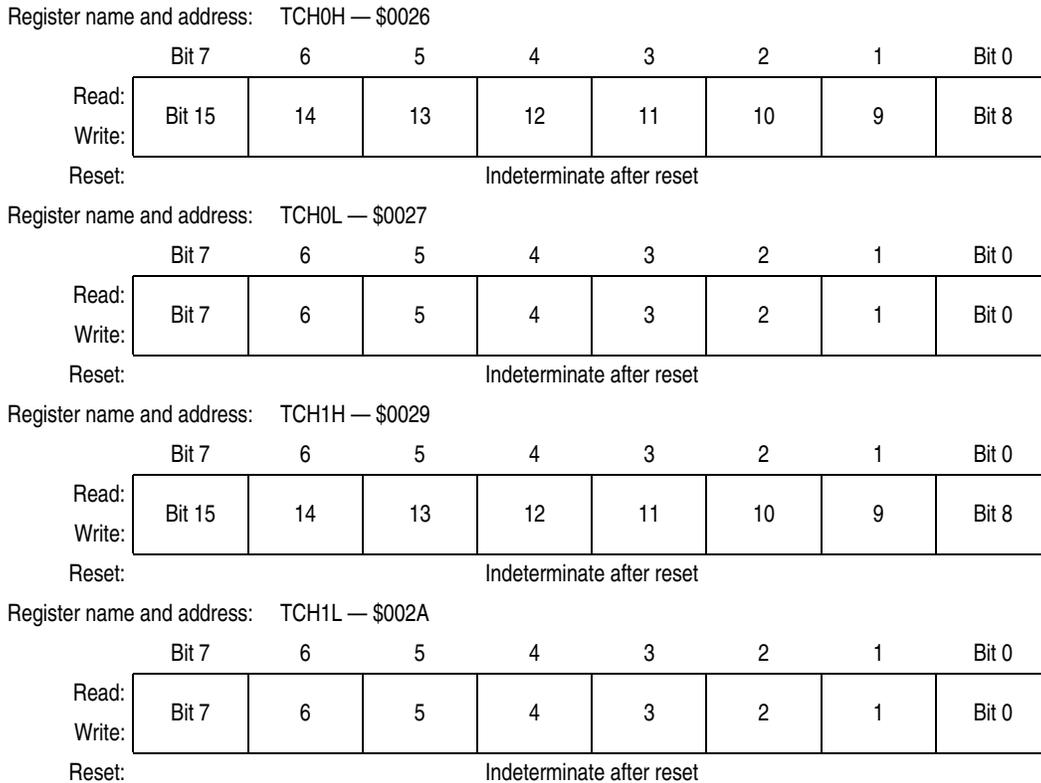
**Figure 15-9. CHxMAX Latency**

### 15.8.5 TIM Channel Registers

These read/write registers (TCH0H/L and TCH1H/L) contain the captured TIM counter value of the input capture function or the output compare value of the output compare function. The state of the TIM channel registers after reset is unknown.

In input capture mode ( $MSxB:MSxA = 0:0$ ), reading the high byte of the TIM channel x registers (TCHxH) inhibits input captures until the low byte (TCHxL) is read.

In output compare mode ( $MSxB:MSxA \neq 0:0$ ), writing to the high byte of the TIM channel x registers (TCHxH) inhibits output compares until the low byte (TCHxL) is written.



**Figure 15-10. TIM Channel Registers (TCH0H/L and TCH1H/L)**

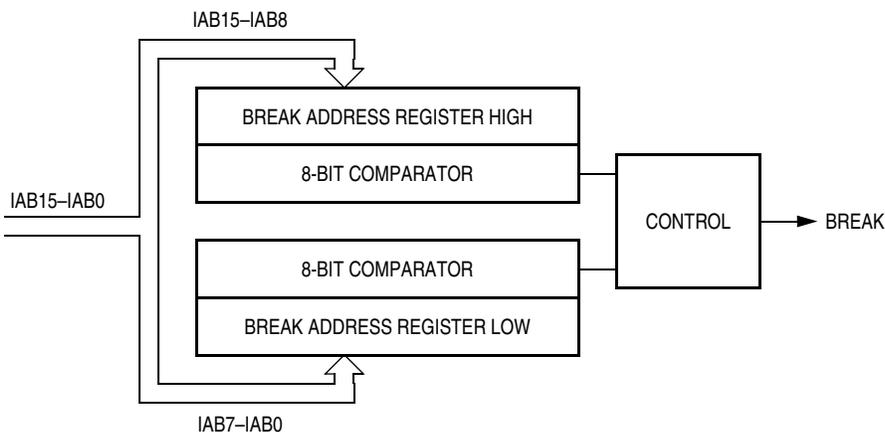


Figure 16-1. Break Module Block Diagram

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$FE00	SIM Break Status Register (SBSR) See page 172.	Read:	0	0	0	1	0	0	BW	0
		Write:	R	R	R	R	R	R	NOTE	R
		Reset:	0	0	0	1	0	0	0	0
\$FE03	SIM Break Flag Control Register (SBFCR) See page 173.	Read:	BCFE	R	R	R	R	R	R	R
		Write:								
		Reset:	0							
\$FE09	Break Address Register High (BRKH) See page 172.	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$FE0A	Break Address Register Low (BRKL) See page 172.	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$FE0B	Break Status and Control Register (BRKSCR) See page 171.	Read:	BRKE	BRKA	0	0	0	0	0	0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$FE02	Break Auxiliary Register (BRKAR) See page 173.	Read:	0	0	0	0	0	0	0	BDCOP
		Write:								
		Reset:	0	0	0	0	0	0	0	0

Note: Writing a 0 clears BW.

= Unimplemented      R = Reserved

Figure 16-2. I/O Register Summary

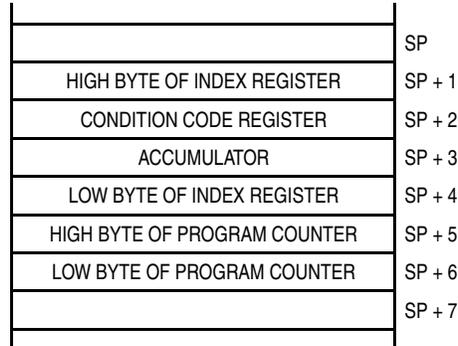
### 16.2.1.2 CPU During Break Interrupts

The CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with \$FFFC and \$FFFD (\$FEFC and \$FEFD in monitor mode)

The break interrupt begins after completion of the CPU instruction in progress. If the break address register match occurs on the last cycle of a CPU instruction, the break interrupt begins immediately.

The MCU executes the SWI and PSHH instructions when it enters monitor mode. The RUN command tells the MCU to execute the PULH and RTI instructions. Before sending the RUN command, the host can modify the stacked CPU registers to prepare to run the host program. The READSP command returns the incremented stack pointer value, SP + 1. The high and low bytes of the program counter are at addresses SP + 5 and SP + 6.



**Figure 16-14. Stack Pointer at Monitor Mode Entry**

### 16.3.2 Security

A security feature discourages unauthorized reading of FLASH locations while in monitor mode. The host can bypass the security feature at monitor mode entry by sending eight security bytes that match the bytes at locations \$FFF6–\$FFFD. Locations \$FFF6–\$FFFD contain user-defined data.

**NOTE**

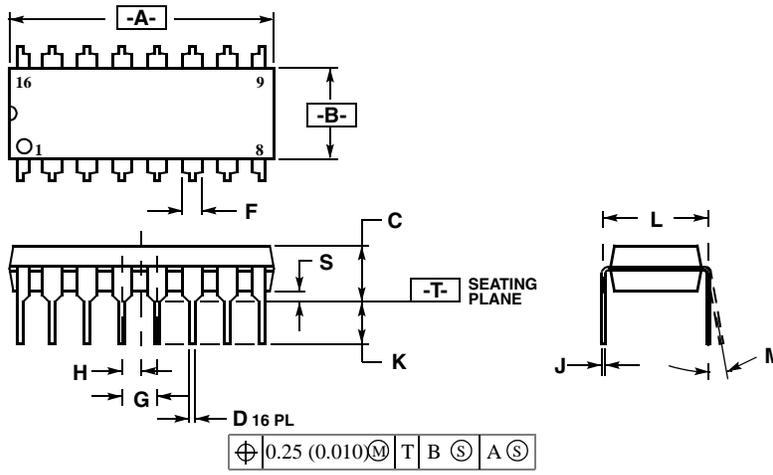
*Do not leave locations \$FFF6–\$FFFD blank. For security reasons, program locations \$FFF6–\$FFFD even if they are not used for vectors. If FLASH is erased, the eight security byte values to be sent to the MCU are \$FF, the unprogrammed state of the FLASH.*

During monitor mode entry, a reset must be asserted. PTA1 must be held low during the reset and 24 CGMXCLK cycles after the end of the reset. Then the MCU will wait for eight security bytes on PTA0. Each byte will be echoed back to the host. See Figure 16-15.

If the received bytes match those at locations \$FFF6–\$FFFD, the host bypasses the security feature and can read all FLASH locations and execute code from FLASH. Security remains bypassed until a reset occurs. After any reset, security will be locked. To bypass security again, the host must resend the eight security bytes on PTA0.

If the received bytes do not match the data at locations \$FFF6–\$FFFD, the host fails to bypass the security feature. The MCU remains in monitor mode, but reading FLASH locations returns undefined data, and trying to execute code from FLASH causes an illegal address reset.

### 18.3 16-Pin Plastic Dual In-Line Package (PDIP)

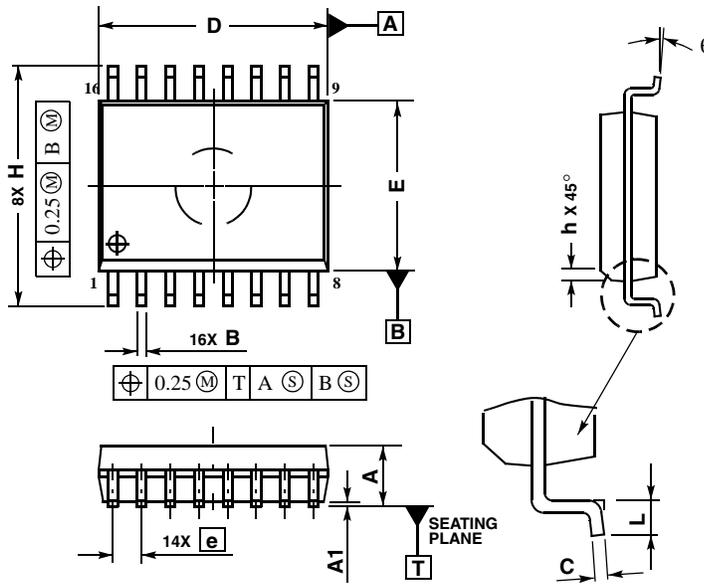


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 (0.010).
6. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.760	18.80	19.30
B	0.245	0.260	6.23	6.60
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.050	0.070	1.27	1.77
G	0.100	BSC	2.54	BSC
H	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.120	0.140	3.05	3.55
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.015	0.035	0.39	0.88

### 18.4 16-Pin Small Outline Package (SOIC)



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27	BSC
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
theta	0°	7°